



AEMTEC AT A GLANCE

Your Strategic Technology and Production Partner for customized Micro- and Optoelectronics

SERVICES

- ✓ Concept/Process Development
- Prototyping
- ✓ Supply Chain Management
- ✓ Test Systems / Qualification
- ✓ Industrialization / Volume Production
- ✓ Product Life Cycle Support
- ✓ Extensive Cleanroom Production (ISO 5 to 8)

CERTIFICATIONS

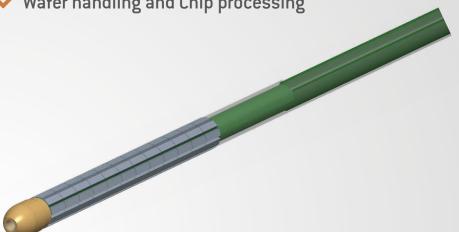
ISO 9001 ISO 13485

ISO 14001

3D PACKAGING APPROACH -MINIMALLY INVASIVE MEDICAL APPLICATION CATHETER



- Electronics packaging for medical applications
- ✓ Imaging and treatments with the help of ultrasound waves
- ✓ Wafer handling and Chip processing



PROCESS STEPS

- Au stud bumping
- Isotropic conductive adhesive (ICA) printing
- ✓ Wafer dicing
- Flip chip attach
- Capillary underfill
- Substrate dicing
- 3D probe forming and encapsulation

Contact!

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www.AEMtec.com